

## Descriptions

These N-channel MOSFET are produced using advanced plane MOSFET Technology, which provides Low on-state resistance, high switching performance and excellent quality. These devices are suitable device for SMPS, high Speed switching and general purpose applications.

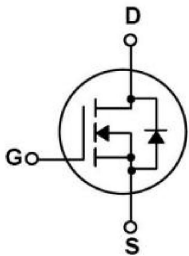
## Features

- VDS =600V
- ID = 20A @VGS =10V
- RDS(ON) (Typ)=160mΩ @VGS =10V

## Applications

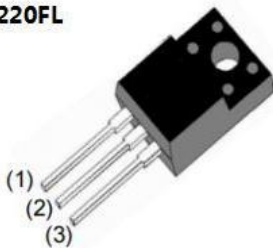
- Power Supply
- PFC
- High Current, High Speed Switching

## Equivalent Circuit



## Pinning

TO-220FL



PIN1:Gate PIN 2:Drain PIN 3:Source

## Marking

Marking	8205
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**Absolute Maximum Ratings(Ta=25°C)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DSS</sub>	600	V
Drain Current	I <sub>D</sub> (T <sub>C</sub> =25°C)	20	A
Drain Current - Pulsed	I <sub>DM</sub>	60	A
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Single Pulsed Avalanche Energy	E <sub>AS</sub>	405	mJ
Avalanche Current	I <sub>AS</sub>	12.5	A
Power Dissipation	P <sub>D</sub> (T <sub>C</sub> =25°C)	34	W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C
Junction-to-Case	R <sub>θJC</sub>	3.6	°C/W
Junction-to-Ambient	R <sub>θJA</sub>	80	°C/W

**Electrical Characteristics(Ta=25°C)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	600			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =600V V <sub>GS</sub> =0V T <sub>J</sub> =25°C			5.0	μA
Gate-Body Leakage Current, Forward	I <sub>GSS</sub>	V <sub>GS</sub> =±30V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250μA	2.5		4.5	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V I <sub>D</sub> =10A		160	190	mΩ
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V I <sub>SD</sub> =1A T <sub>J</sub> =25°C			1.2	V
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V f = 1.0MHz		3.5		Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =100V V <sub>GS</sub> =0V f=1.0MHz		1725		pF
Output Capacitance	C <sub>oss</sub>			90		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			2.5		pF
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =400V I <sub>D</sub> =10A R <sub>G</sub> =25Ω V <sub>GS</sub> =10V		26		ns
Turn-On Rise Time	t <sub>r</sub>			39		ns
Turn-Off Delay Time	t <sub>d(off)</sub>			115		ns
Turn-Off Fall Time	t <sub>f</sub>			32		ns

## Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Diode Forward Current	$I_S$			20		A
Total Gate Charge	$Q_g$	$V_{DS}=480V \quad I_D=10A$ $V_{GS}=10V$		38.2		nC
Gate-Source Charge	$Q_{gs}$			10		nC
Gate-Drain Charge	$Q_{gd}$			13		nC
Reverse recovery time	$t_{rr}$	$V_R=400V, \quad I_F=10A,$ $di_F/dt=100A/\mu s$		141		ns
Reverse recovery charge	$Q_{rr}$			0.85		uC

Electrical Characteristic Curve

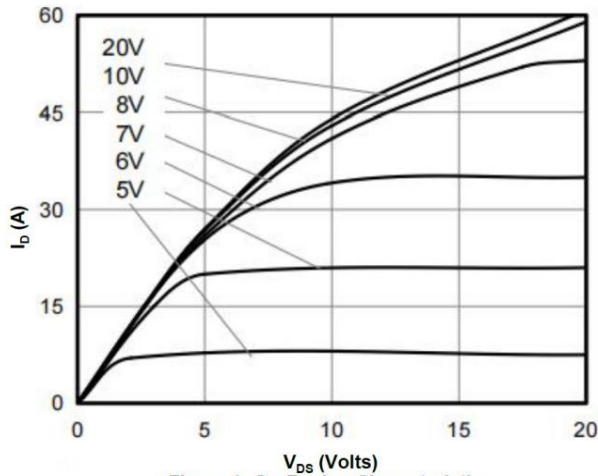


Figure 1: On-Region Characteristics

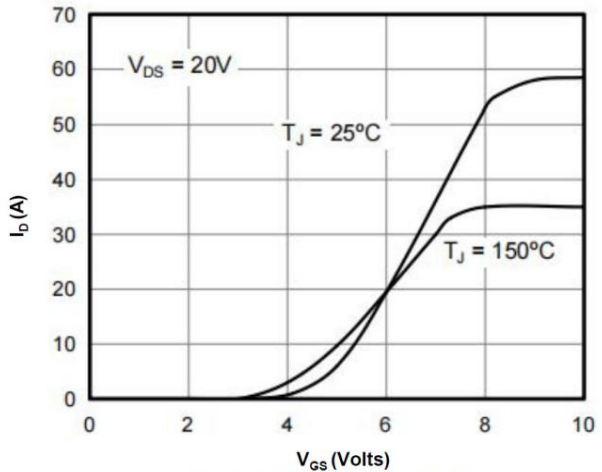


Figure 2: Transfer Characteristics

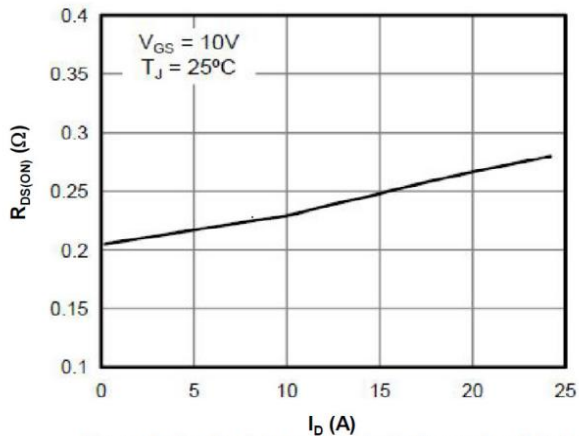


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

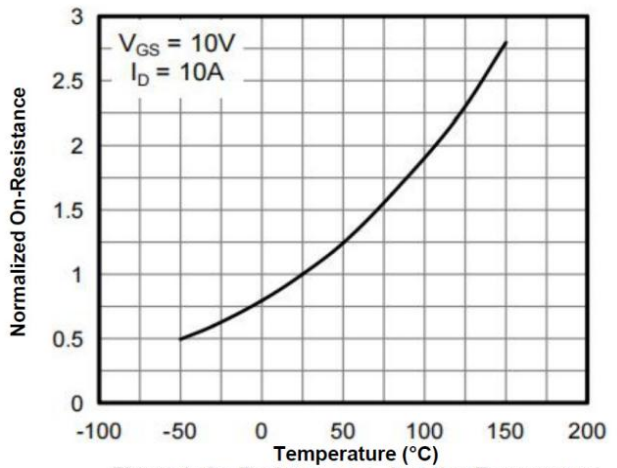


Figure 4: On-Resistance vs. Junction Temperature

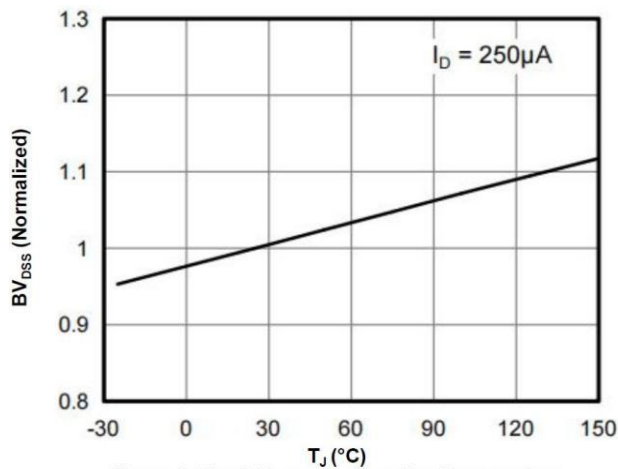


Figure 5: Break Down vs. Junction Temperature

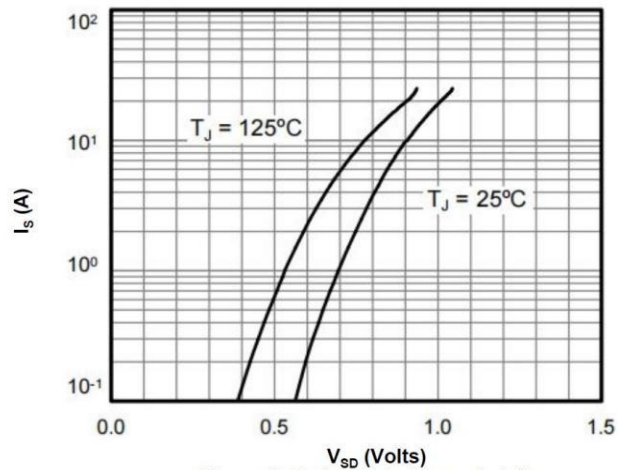


Figure 6: Body-Diode Characteristics

Electrical Characteristic Curve

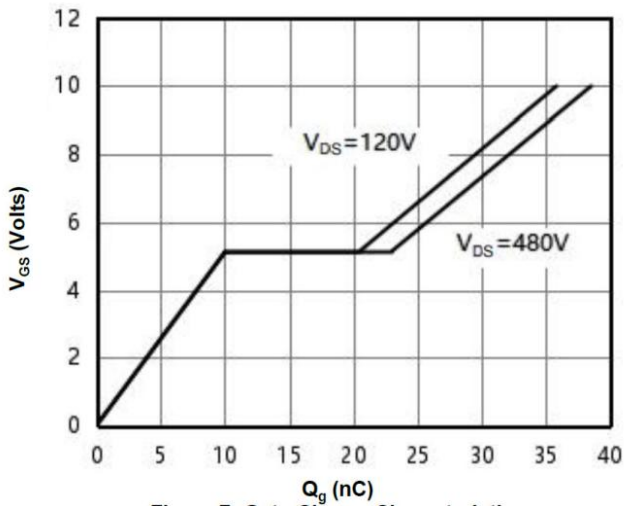


Figure 7: Gate-Charge Characteristics

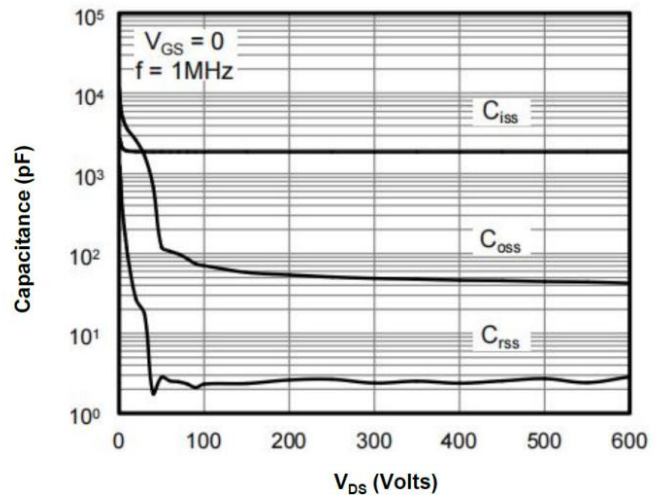


Figure 8: Capacitance Characteristics

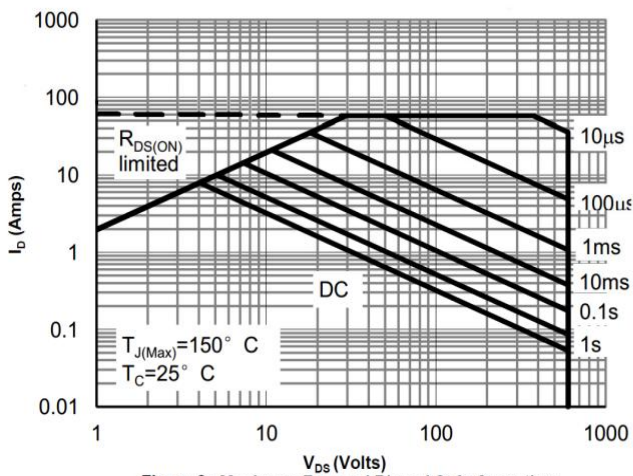


Figure 9: Maximum Forward Biased Safe Operating Area

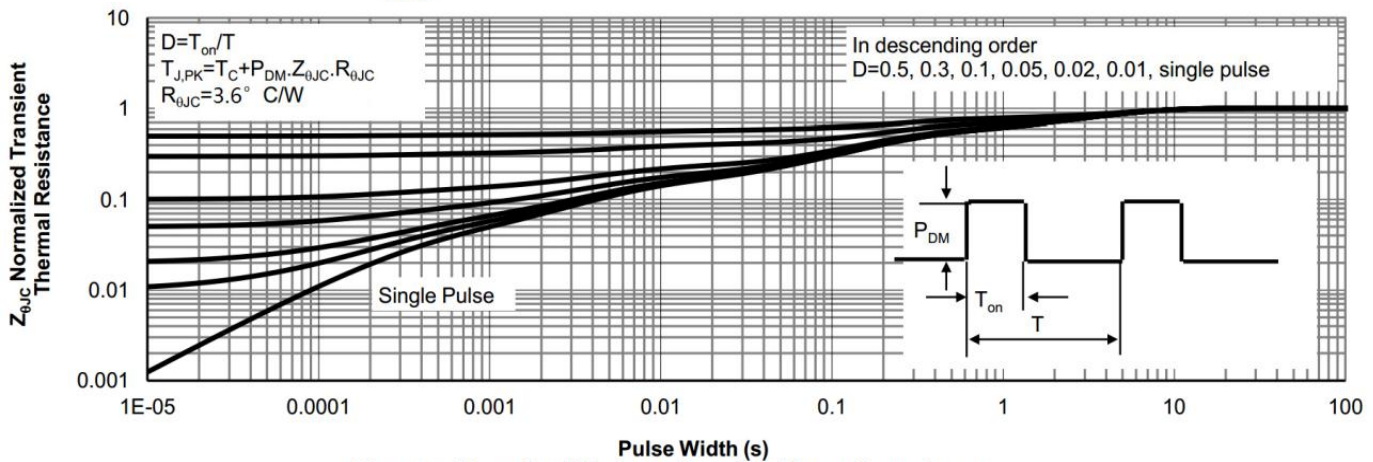
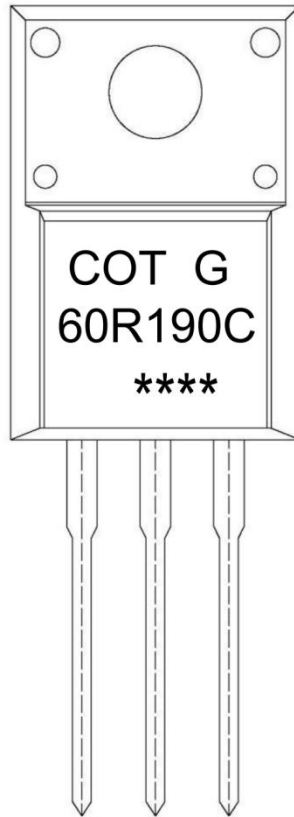


Figure 10: Normalized Maximum Transient Thermal Impedance

**Marking Instructions**



- Note:**
- COT: Company Logo
  - G: Halogen Free
  - 60R190C: Product Type.
  - \*\*\*\*: Lot No. Code, code change with Lot No.

**Packaging SPEC.**

**TUBE INFORMATION**

Package Type	Units					Dimension (unit: mm <sup>3</sup> )		
	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Tube	Inner Box	Outer Box
TO-220FL	50	20	1,000	5	5,000	532×33×7.0	555×164×50	575×290×180

Package Dimensions

TO-220FL

单位: mm

